



Material Content Data Sheet



Sales Product Name	TLE4678GM			Issued	20. July 2018			
MA#	MA001154500							
Package	PG-DSO-14-30			Weight*	143.30 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.312	2.31	2.31	23115	23115
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		105	
	non noble metal	zinc	7440-66-6	0.060	0.04		421	
	non noble metal	iron	7439-89-6	1.207	0.84		8423	
wire	non noble metal	copper	7440-50-8	49.007	34.20	35.09	342001	350950
	noble metal	gold	7440-57-5	0.273	0.19	0.19	1907	1907
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1195
encapsulation	plastics	epoxy resin	-	7.879	5.50		54987	
	inorganic material	silicondioxide	60676-86-0	77.595	54.15	59.77	541507	597689
leadfinish	non noble metal	tin	7440-31-5	1.241	0.87	0.87	8664	8664
plating	noble metal	silver	7440-22-4	1.030	0.72	0.72	7186	7186
glue	plastics	acrylic resin	-	0.331	0.23		2308	
	noble metal	silver	7440-22-4	1.172	0.82	1.05	8181	10489
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com